

Title (en)

SUBSTRATE WITH AT LEAST TWO METALLIZED POLYMER BUMPS FOR SOLDERED CONNECTION TO WIRING

Title (de)

SUBSTRAT MIT MINDESTENS ZWEI METALLISIERTEN POLYMERHÖCKERN FÜR DIE LÖTVERBINDUNG MIT EINER VERDRAHTUNG

Title (fr)

SUBSTRAT COMPORTANT AU MOINS DEUX SAILLIES DE POLYMERE METALLISEES POUR CONNEXION PAR BRASAGE AVEC UN CABLAGE

Publication

EP 1186031 A1 20020313 (DE)

Application

EP 00938553 A 20000511

Priority

- DE 0001497 W 20000511
- DE 19923247 A 19990520

Abstract (en)

[origin: WO0072378A1] A substrate (S) with at least two metallized polymer bumps (PS), especially a polymer stud grid array, is configured in such a way that the polymer bumps (PS) have at least one step (ST) and at least one elevation (E). The geometry of the solder bumps (PS) ensures that the soldered connections to the wiring (V) are secure and guarantees reproducible layer thickness for the solder (L).

IPC 1-7

H01L 23/13; H01L 23/498; H05K 3/34

IPC 8 full level

H01L 21/60 (2006.01); **H01L 23/13** (2006.01); **H05K 3/34** (2006.01)

CPC (source: EP KR)

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C-Set (source: EP)

H01L 2924/0002 + **H01L 2924/00**

Citation (search report)

See references of WO 0072378A1

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